

PID system for SPD detector and TOF technology for barrel and forward parts

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#### Outlook

- SPD PID
- Brief results of ALICE TOF R&D
- Key point for high-rate RPC new low resistive material with high surface quality
- CMB R&D results for semiconductive ceramics and low resistive glass
- Search for optimal resistance using ceramic electrodes.
- First simulations for SPD PID
- Conclusion and future plans



# SPD DETECTOR LAYOUT FOR THE MOMENT



- PID has two rather different parts: barrel and forward
- PID should serve till maximum momentum of primary beam.
- PID should consist of TOF and HMPID.



# BRIEF RESULTS OF ALICE TOF R&D







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### TOF ALICE – huge Time-of-Flight system ever done





### BOLOGNA DESIGN FOR ALICE TOF(AS EXAMPLE FOR BARREL PID)





Creation of new technology and its adaptation for mass production The detector is recognized as the main technological success of the ALICE collaboration

# PERFORMANCE OF THE ALICE TIME-OF-FLIGHT DETECTOR AT THE LHC

ITEP





### KEY POINT FOR HIGH-RATE RPC – NEW LOW RESISTIVE MATERIAL WITH HIGH SURFACE QUALITY

#### NEW LOW RESISTIVE MATERIAL SEARCH



A. Akindinov, V. Ammosov, V. Gapienko, et al., Nucl. Instr. and Meth. A 572 (2007) 676-681

### CMB TOF R&D RESULTS FOR SEMICONDUCTIVE CERAMICS AND LOW RESISTIVE GLASS



# $SI_3N_4/SIC CERAMIC$



- Thickness d = 2 mm
- Thickness uniformity 10 µm
- Surface roughness 100 nm
- Bulk resistivity  $\rho = 10^7 10^{12} \Omega \cdot cm$
- Permittivity  $\varepsilon_r = 10 20$
- Rad. hardness proved at 10<sup>13</sup> n<sub>er</sub>/cm<sup>2</sup>
- DC measurement (> 1 C/cm<sup>2</sup>) shows non-ohmic behavior



percent by weight M.

L. Naumann et al., NIM A 628 (2011) 138 A. Laso Garcia et al., JINST 7 (2012) 10012

rough ceramics as sintered: Ø ≈ 30 cm d ≈ 3.5 mm

mixing ratio: Si<sub>3</sub>N<sub>4</sub>/SiC (80%/20%)





Four-gap device with 300 mm gas gaps. Resolution 110 ps for U=5.7 kV !!!But very high level of dark current  $> 100 \ \mu$ A!!!

ITEP cathode ceramics ceramics Cathode

100

80

efficiency



L. Naumann, R. Kotte, D. Stach, J. Wustenfeld Nuclear Instruments and Methods in Physics Research A 635 (2011) S113–S116



## IMPROVE OF TECHNOLOGY







bacang Ergebeis 8be[A-0] 168,3µm reite[C-0] 1358,1µm









Si3N4/SiC



20 000 r.pm. rotation speed and 15 mm/min processing speed

#### ROSSENDORF ELECTRODES 24X24 MM<sup>2</sup> AND 50X50 MM<sup>2</sup>





Q











#### NEW AL<sub>2</sub>O<sub>3</sub> ELECTRODES 24X24 MM<sup>2</sup>(ACTIVE SIZE 20X20 MM<sup>2</sup>)



Manuara Cogebrie Manuala-01 193,44m Resite[C-D] 648,84m



















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# SEARCH FOR OPTIMAL RESISTANCE USING CERAMIC ELECTRODES

#### SEARCH FOR MINIMAL POSSIBLE RESISTANCE





20 10

20

\_//

40



Sigma

×10³

180









10000 20000

10000 20000

We selected value of resistance 4\*10<sup>9</sup> Ohm\*cm as minimal

10000 20000

Journal of Physics: Conf. Series 798 (2017) 012136

0

10000 20000

120

140

160

100

80

Flux, [Hz/cm<sup>2</sup>]

60

#### **TESTS WITH PADI ELECTRONICS**





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#### E=88kV/cm; U<sub>thr</sub> =180mV Entries: 0 Eff = 0.0% Entries: 207 Eff = 66.3% Entries: 11 Eff = 0.6% Entries: 0 Eff = 0.0% Entries: 1 Eff = 0.0% Entries: 2 Eff = 0.1% Entries: 0 Eff = 0.0% Entries: 0 Eff = 0.0% Entries: 1 Eff = 0.0% Entries: 1 Eff = 0.0% Entries: 1 Eff = 0.0% Eff = 74.8 Eff = 0.4% Entries: 0 Eff = 0.0% Entries: 2 Eff = 0.1% Entries: 0 Eff = 0.0% Entries: 0 Eff = 0.0% Entries: 4 Eff = 0.1% Eff = 68.2% Eff = 0.8% Entries: 0 Eff = 0.0% Entries: 1 Eff = 0.0% Entries: 14 Eff = 0.5% Entries: 3 Eff = 0.1% Entries: 1 Eff = 0.0% Eff = 0.8% Entries: 3 Eff = 0.1% Entries: 0 Eff = 0.0% Entries: 1 Eff = 0.0% Entries: 1 Eff = 0.51 Entries: 0 Eff = 0.0% Entries: 0 Eff = 0.0% Entries: 2 Eff = 0.1% Entries: 0 Eff = 0.0% Entries: 1 Eff = 0.4% Entries: 0 Eff = 0.0% Entries: 0 Eff = 0.0% Entries: 20 Eff = 0.6% Entries: 3 Eff = 0.1% Eff = 62.4% Eff = 0.0% Entries: 7 Eff = 0.2% Entries: 241 Eff = 70.8% Entries: 1 Eff = 0.0% Entries: 0 Eff = 0.0% Entries: 0 Eff = 0.0% Entries: 1 Eff = 0.0% Entries: 1 Eff = 0.0% Entries: 3 Eff = 0.1% ToT cross-talk probability in all 8 RPCs ≤ 1.2%



#### BFTC preproduction module



Preproduction BFTC module is being developed.

64 channels, 32x8 cm active area. Two identical PCB, but one is flipped.

PCB board design is finished.



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#### **PCB** layout

100 Ohm lines to transport signals to PADI.

50 Ohm lines for test pulse.

#### 6 layers PCB. 8 lines for HV (4 cells per one HV channel).





#### st1 V116 36 36 36 36 36 *4*4<u>4</u> (the party of the second secon IV2 **A** V2 est2 2 TOP Core1 (Ro4350B) IN1 Prepreg (2xRo4450B) IN2 Core2 (Ro4350B) IN3 Prepreg (2xRo4450B) IN4 Core3 (Ro4350B) BOT 8 3 arameter Entry Units C Micron C Millimetre محمع أقفقة أمحمع Mils C Microns C Inches C Millimetres olerance Minimum Maximur Substrate 1 Height 7.4803 + ± 0.0000 7.4803 7.4803 Calculate Tolerance Minimum Maximum anar Waveguide With Ground 28 Substrate 1 Dielect 3.5400 + ± 0.0000 3.5400 3.5400 Calculate Substrate 1 Height H1 20.0000 + ± 0.0000 20.0000 Calculate Edge-Coupled Offset Stripline 1B1A 20.0000 + ± 0.0000 20.0000 Calculate Substrate 2 Height H2 Substrate 1 Dielectric Er1 3.4800 + ± 0.0000 3.4800 3.4800 Calculate Substrate 2 Dielecti 3.4800 + ± 0.0000 3.4800 3.4800 Calculate S1 W2 Substrate 2 Height H2 [ 7.4803 + ± 0.0000 7.4803 7.4803 Calculate ower Trace Width 33.9998 + ± 0.0000 33.9998 33.9998 Substrate 2 Dielectric Er2 3.5400 + ± 0.0000 3.5400 Calculate Linner Trace Width 36.9999 + ± 0.0000 36.9999 36.9999 Calculate H1 Ground Strip Separa 12.0000 + ± 0.0000 12.0000 Calculate Lower Trace Width W1 9.0000 + ± 0.0000 9.0000 9.0000 Frace Thickness 1.3780 + ± 0.0000 1.3780 1.3780 Calculate Upper Trace Width W2 9.0000 + ± 0.0000 9.0000 Calculate Coating Above Substrate 1.0000 + ± 0.0000 1.0000 1.0000 Trace Separation S1 21.0000 + ± 0.0000 21.0000 Calculate Coating Above Trace C2 1.0000 ± ± 0.0000 1.0000 1.0000 Trace Thickness T1 0.7087 + ± 0.0000 0.7087 0.7087 Calculate Coating Dielectric CEr 4.2000 ± ± 0.0000 4.2000 4.2000 lotes: (First 5 lines will print) Interface S dd your comments here Standard Zo 50.89 50.89 50.89 (L'alculate) Impedance Differential Impedance Zdiff 101.88 101.88 101.88 (Calculate)

# SIZE FOR PID SYSTEM







As we see PID should be thin Not thick than 50 cm!



# SIMULATION DONE SO FAR (BY SEREGEY KISELEV)

URQMD p+p at maximum energy

No magnetic field

Simple plane at barrel and forward parts

=> mult. per ev.: 12.40 all, 7.78 charged (2.92 TOFbarrel, 4.86TOFend-cups)

 $\Rightarrow$  TOF: barrel: S=6.33 \* 10<sup>5</sup> cm<sup>2</sup>, 4.61 \* 10<sup>-6</sup> tracks/cm<sup>2</sup>,

 $\Rightarrow$  end-cups: S=2.04 \*10<sup>5</sup> cm<sup>2</sup>, 2.39\*10<sup>-5</sup> tracks/cm<sup>2</sup>,

===> at sigma\_pp=40.0 mb and Lumi=2.0e<sup>32</sup> cm<sup>-2</sup> s<sup>-1</sup> ----> 8.0e<sup>06</sup> coll. per sec

 $\rightarrow$  ~3 MHz (should be free-streaming readout)

۷	/ <i>s</i> , GeV	$\sigma_{tot}$ , mb	Charged multiplicity	Neutral (γ) multiplicity
	13	38.4	5.9	4.6 (3.8)
	20	38.9	7.2	6.0 (5.0)
	26	39.7	7.8	6.5 (5.5)

Conceptual design of the Spin Physics Detector (For comparison)



6 7 p (GeV/c)

(float + low resistive glass)

HMPID (PANDA like DIRC?)

p (GeV/c)

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11

fishing line 0.22mm

10nF

R10K0hm

signal strip–PCB 0.1mm, Cu–0.035mn

# **CONCLUSION+PLANS**



After very first simulation:

- > We can use different TOF-RPC technic and we need to have HMPID:
- 1. Forward part Ceramic + MRPC (low resistive glass with pads and strips) + MRPC (float glass with strips)
- 2. Barrel part: MRPC (float glass with strips)
- > At next step need more realistic simulation and production of first modules:
- Ceramic:
- 1. We have to estimate maximum cell size to avoid double hit
- 2. We need to know beam pipe diameter to define maximum rate we can have
- 3. We have to understand maximum input frequency allow for FEE and TDC (rate per  $cm^2 * cell area$ )
- 4. Mass-production of Si<sub>3</sub>N<sub>4</sub>/SiC was confirmed! German grant for HZDR-IKT(Dresden) started from 1 of June2019 liquid phase and hot pressing. Al<sub>2</sub>O<sub>3</sub> will be produces in Dubna technologic park by C-Component.
  □ Glass chambers
- Fixed value of resistance (5\*10<sup>10</sup>-1\*10<sup>11</sup>) Ohm\*cm and maximal size 30x32 cm<sup>2</sup>
- 1. Chamber design : no problem for float glass (even 1.2 meter long like in ALICE), but need to know maximum size for low resistive if still maximum size about 30 cm?
- 2. Need to precise define region with rate  $< 500 \text{ Hz/cm}^2$  to find border between low resistive and float glass
- > All of us should think what kind of HMPID we can use from point of view physics/cost
- First ceramic prototype we are going do design just after we defined cell size. PCB will be the same as for CBM BFTC.



# THANK YOU FOR ATTENTION!